

ETSC Technologies Europe

ETSC Technologies Europe is a professional Photonics solution provider established in Louvain-la-Neuve since 2014. We provide wide range of optoelectronic devices for scientific research and industrial applications in the fields of optical fiber communication, laser sensing, terahertz imaging and laser processing.

Great service through worldwide partnership

ETSC works with its partners from worldwide to support clients all around Europe. These partners are NTT-AT, IRDAION and SURUGA SEIKI.

Not just a solution provider

ETSC is not only a solution provider but also but also a developer.

In 2016, we released our own developed distributed fiber sensing interrogator-OCI-1500 using OFDR method for optical link diagnostic and temperature/strain measurement. This device can be applied to civil engineering such as pipeline, construction, aerospace, automotive, et cetera. It can also be applied to optical fiber communication to detect the structure of PICs, such as the defects of micro bends, splicing points.

In 2017, we have developed a component burn-in system-LHX series which can measure the life circle of PD, LD and APD from chip to component level.

Our Vision

Our goal is to provide great service and keep developing novel systems to support various applications of our clients. We believe that with our experience and through our present and future collaborations with other photonics specialists throughout the world, we can bring a one-step-ahead technology to the Photonics industry.

Our website

<https://www.etsc-tech.be/>

Our Recruitment

MEMS chip design and development engineer

Job Responsibilities:

1. Responsible for MEMS sensor chip layout design, structural design, process confirmation and development;

2. Responsible for the simulation of MEMS sensor chips, using finite element analysis software for multi-physics simulation, writing simulation programs, etc.;
3. Responsible for the development of MEMS sensor chip process flow, including laboratory process verification and mass production process development and optimization;
4. Responsible for microscopic analysis of MEMS sensor chips, using SEM, X-RAY, etc. for chip failure analysis;
5. Maintain close contact with the foundry, and commit to promoting the MEMS production process from prototype to mass production;
6. Analyze MEMS product data in production and engineering tests, verify MEMS process changes, design and execute engineering tests to solve process problems or optimize process performance;
7. Assist in completing the design, testing and verification of related module-level products.

Profile:

1. Doctor degree or above, major in electronics, microelectronics, MEMS or semiconductor materials;
2. Proficiency in using MEMS layout design software for layout design, with related work experience in plate making and plate casting;
3. Proficiency in using related design and simulation software for chip structure design and finite element analysis, including thermoelectric, fluid, piezoresistive, piezoelectric and other multi-physical field simulations;
4. Understand the conventional MEMS process of chip processing, such as photolithography, etching, coating, etc., and be able to formulate the processing process of chip samples;
5. Ability to test and analyze chip performance indicators, experience in MEMS pressure chip design is preferred.

Are you interested in working in a growing company with positive work atmosphere and young team, in a position where you can take on engineer tasks, contributing to the backbone and growth of the company?

Then be sure to send your CV and cover letter to huiwinw@etsc-tech.com; judyh@etsc-tech.com .